

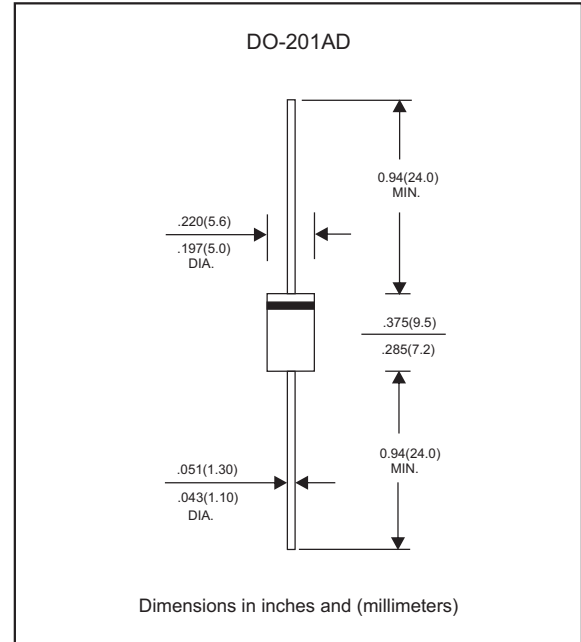
Features

- Axial lead type devices for through hole design
- High current capability.
- Superfast recovery time for switching mode application,
- High surge capability.
- Glass passivated chip junction structure.
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen free parts, ex. SF31G-H.

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, DO-201AD
- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position : Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	Ambient temperature = 55°C	I_O			3.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			125	A
Reverse current	$V_R = V_{RRM} \quad T_J = 25^\circ\text{C}$	I_R			5.0	μA
	$V_R = V_{RRM} \quad T_J = 125^\circ\text{C}$				100	
Thermal resistance	Junction to ambient	$R_{\theta JA}$		20		$^\circ\text{C/W}$
	Junction to case	$R_{\theta JC}$		12		$^\circ\text{C/W}$
	Junction to lead	$R_{\theta JL}$		8		$^\circ\text{C/W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		50		pF
Storage temperature		T_{STG}	-65		+175	$^\circ\text{C}$

SYMBOLS	V _{RRM} ^{*1} (V)	V _{RMS} ^{*2} (V)	V _R ^{*3} (V)	V _F ^{*4} (V)	t _{rr} ^{*5} (ns)	Operating temperature T _J , (°C)
SF31G	50	35	50	0.95	35	-55 to +150
SF32G	100	70	100			
SF33G	150	105	150			
SF34G	200	140	200			
SF35G	300	210	300	1.25		
SF36G	400	280	400			
SF37G	500	350	500	1.70		
SF38G	600	420	600			

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage@ $I_F=3.0\text{A}$

*5 Maximum Reverse recovery time, note 1

Note 1. Reverse recovery time test condition, $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$

Rating and characteristic curves

FIG.1- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC

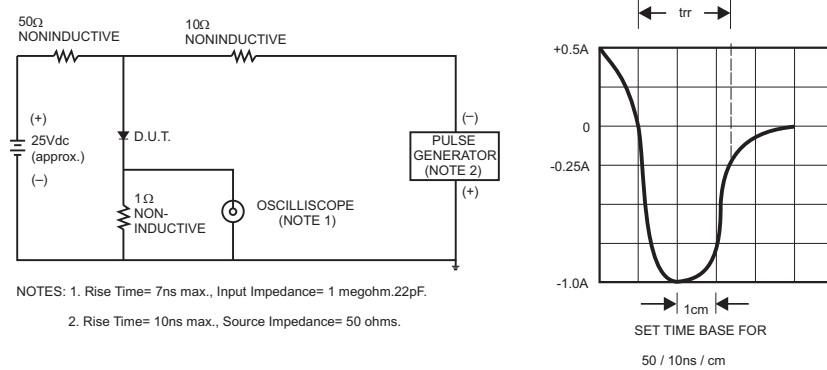


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

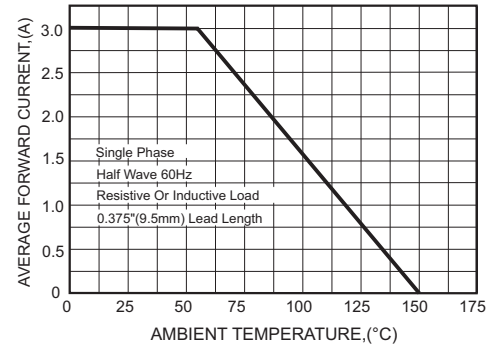


FIG.3-TYPICAL FORWARD CHARACTERISTICS

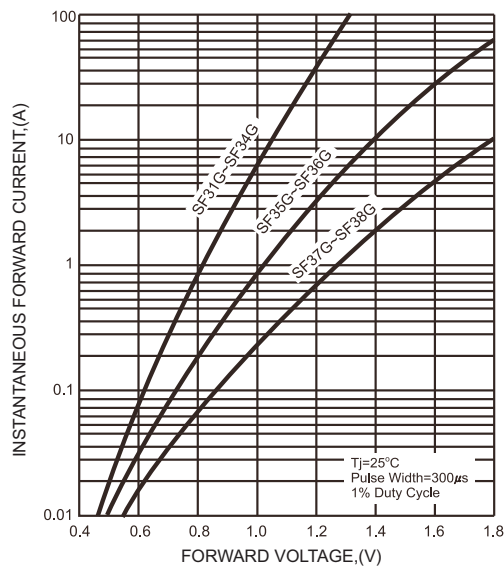


FIG.4-TYPICAL REVERSE CHARACTERISTICS

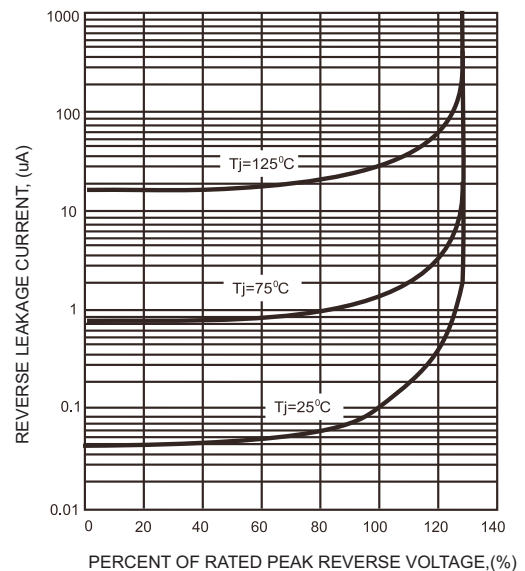


FIG.5-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

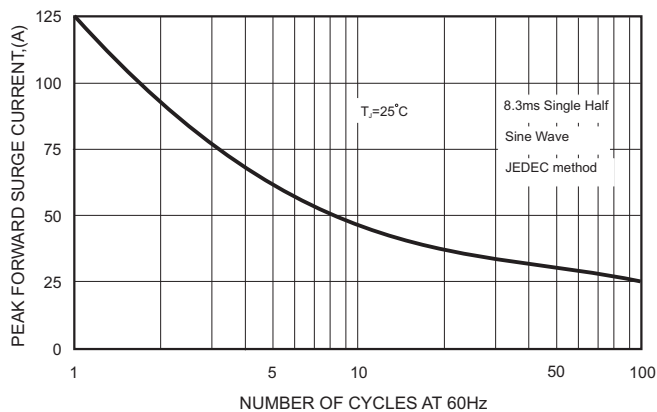
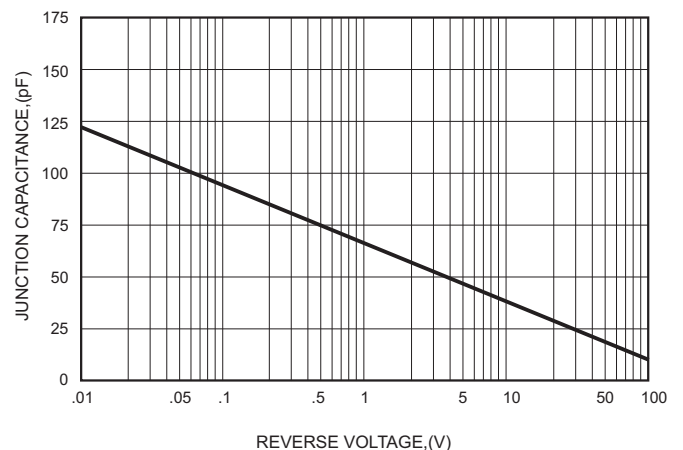


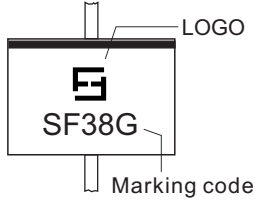
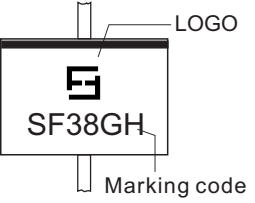
FIG.6-TYPICAL JUNCTION CAPACITANCE



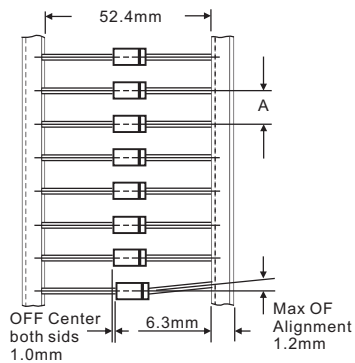
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode	1  2	1  2

Marking

Type number	Marking code	Example	
SF31G SF32G SF33G SF34G SF35G SF36G SF37G SF38G	SF31G SF32G SF33G SF34G SF35G SF36G SF37G SF38G	For Halogen Device 	For Halogen-free Device 

Taping specifications for AXIAL devices



AMMO PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-201AD	1,250	258 * 75 * 143	405 * 270 * 320	12,500	14.0

Suggested thermal profiles for soldering processes

1. Lead free temperature profile wave-soldering

